

13985

Memory arrangement and method for operating such a memory arrangement

- 5 The present invention relates to a memory arrangement according to the preamble of patent claim 1 and to a method for operating a memory arrangement.

10 Memory arrangements of the generic type are known, for example, in the form of semiconductor memory chips of the SRAM type or of one of the different rewritable ROM types such as EAROM, EPROM, EEPROM, flash memories etc. All of these chip types which certainly contain, as
15 as, for example, silicon have the feature in common that the information stored in them is read out in a nondestructive manner, i.e. the information stored in them is also retained in them during the reading-out operation (in contrast to this, stored information is
20 read out from DRAM memory arrangements in a destructive manner, thus resulting in the information that has been read out having to be written back again to the affected memory cells immediately after it has been read out).

25

As the miniaturization of the structures of integrated circuits advances and thus also as the miniaturization of the structures of memory arrangements of the generic type advances, an attempt has recently been made to
30 provide memory arrangements whose storage mechanism is no longer based on the storage mechanisms known from semiconductor memories but rather on other storage mechanisms. Examples of such other storage mechanisms which are already generally known are, for example, the
35 ferroelectric type (for example FeRAM) and the magnetic type (for example MRAM). In addition, however, research is also being carried out on memory types which are still largely unknown nowadays: for example, part 2 of the article "Die Zukunft des Speichers [The future of

memory]" was available to the general public on the Internet on 13 October 2003 and can be found using the address

"www.elektroniknet.de/topics/bauelemente/fachthemen/200
5 2/020223".

Said article referred to polymer-based FeRAMs and to an "Ovonics Unified Memory OUM" as future new memory technologies. In addition, pages 118 to 123 of the
10 journal "Elettronica Oggi 316", October 2002 issue, presented a new storage mechanism having future prospects, namely an electrochemical memory using PMC technology (PMC = Programmable Metallization Cell). However, it can be expected in at least some of these
15 storage mechanisms that, in the case of appropriately designed memory arrangements, although reading operations can be effected in a largely nondestructive manner, a certain degree of (quantitative) reduction in the information contained in the affected memory cells,
20 which is caused by the reading-out operation, cannot be avoided. As a result, when repeatedly reading out from one and the same memory cell, the information stored in this memory cell will quantitatively decrease even if it has a digital character, which is generally referred
25 to as degradation. It can thus be foreseen that, after being frequently read out, the amount of information contained in such a memory cell will then have decreased overall to such an extent that this information, during further reading-out operations,
30 will no longer be able to be distinguished, by an evaluation device, from an item of information having the opposite logical content, with the result that read errors will appear.

35 A technically obvious solution to this problem, which is simple to implement, could be to configure each reading operation in such a manner that it is directly followed by a rewriting operation, with the result that an item of information that is read out from a memory

cell in this manner is immediately written back to the same memory cell again, so that, in quantitative terms, it is fully available again for further reading operations on account of the associated signal amplification there. Therefore, such memory arrangements would need to be configured and operated in accordance with the DRAM semiconductor memories which are known everywhere. However, it is also probably reasonable that a rewriting operation, as described above, needs time which in turn would slow down the operation of corresponding memory arrangements to an extent felt to be unacceptable by the user.

Therefore, it is an object of the present invention to configure memory arrangements of the generic type in such a manner that a quantitative reduction in information stored in a memory cell, which is caused by repeatedly reading out the information, is prevented at least to such an extent that no read errors can arise as a result of further reading-out operations. It is also an object to specify a corresponding operating method.

This object is achieved, in the case of a memory arrangement of the generic type, by means of the characterizing features of patent claim 1 and, in the case of a corresponding operating method, by means of the features of patent claim 8. Advantageous refinements and developments are characterized in subclaims.

The invention will be explained in more detail below with reference to a drawing. In this case, figures 1 to 3 show different embodiments of the present invention.

Figure 1 shows part of a first embodiment of the present invention. It is assumed to be implemented in an individual memory chip. As is generally customary, this embodiment has rewritable memory cells MC which

are arranged along word lines WL and bit lines BL, namely at crossovers between the word lines WL and the bit lines BL. The memory cells MC are of a type in which the information stored in them is read out in a largely nondestructive manner. In the case of memory arrangements which are customary nowadays, these may therefore be, for example, semiconductor memories of the abovementioned ROM types or of the static RAM type (SRAM). However, they may also be memory arrangements having storage materials and storage principles which will only gain economic importance in the future. One example of these which may be mentioned, as representative of other possible ways of storing information, are memory arrangements whose storage principle is based on the fact that, when a suitable voltage is applied, a solid electrolyte causes metal ions to migrate within an otherwise insulating electrolyte, with the result that, depending on whether or not a metallically conductive path is formed in this case, a different resistance value is obtained for the solid electrolyte, said resistance value being a synonym for the type of information stored ("logical 0" or "logical 1").

In the case of this first embodiment, the invention now provides for another additional memory cell, namely a so-called flag cell MMC, to be arranged along each word line WL. Said flag cell is preferably of the same memory cell type as the memory cells MC. In particular, it should likewise be of the type that allows an item of information stored in it to be read out in a largely nondestructive manner. In this case, it is also advantageous if it is a memory cell of the nonvolatile type, so that information stored in it is also retained when the supply voltage is switched off. The flag cells MMC can be addressed via the respective word lines WL and via a flag bit line MBL.

When started up for the first time or else after a reset operation (will also be described), these flag cells MMC have a given basic state, i.e. a predetermined type of information is stored in the form of a standard value (either "logical 0" or "logical 1"). Whenever a read access operation to a memory cell MC is then carried out during subsequent operation of the memory arrangement, an item of information that is complementary to the abovementioned standard value is written, according to the invention, to that flag cell MMC which is connected to the same word line WL as the memory cell MC which has been addressed for reading purposes. The content of each flag cell MMC, i.e. the information stored in it, thus always reflects whether at least one of the memory cells MC which are arranged along that word line WL which is associated with the flag cell MMC under consideration has been subjected to a read access operation at least once.

The method according to the invention now provides for memory cells MC, which are arranged along a word line WL whose associated flag cell MMC has a memory content (can be determined by reading out the information stored in the flag cell MMC) which is complementary to the standard value, to be (occasionally) subjected to a refresh operation. As is known, during a refresh operation which is certainly known as such from the operation of dynamic semiconductor memories (DRAM), information stored in the memory cells which are to be refreshed is read out and is written back to the affected memory cells again (usually still in the same read cycle), the signals which represent this information also usually being amplified to their original value using the sense amplifiers which are assigned to the memory cells to be refreshed.

This effect whereby an item of information (whose signal has been amplified) is written back during a refresh operation is advantageously used in this case

to make it possible for an item of information, which is stored in the memory cells MC and which, despite, on the one hand, being able to be read out as such in a largely nondestructive manner, has undergone a certain amount of degradation during repeated reading-out operations, to be returned to its (in quantitative terms) original value again. This makes it possible to avoid the amount of stored information, the amount of which is certainly assumed to decrease somewhat with each reading operation, becoming so small, sometime after being frequently read out, that it can no longer be detected as such by the associated sense amplifier, which is certainly usually configured as a differential amplifier, with the result that a read error arises.

The fact that such a refresh operation takes place only occasionally affords the advantage that considerably less time and energy need to be expended for this than if the information that has been read out were to be written back after each reading operation, as already described at the outset as a theoretical possibility. In addition, the considerably smaller amount of energy expended is also based on the fact that only the memory cells MC along those word lines WL along which the content of memory cells MC has also actually been previously read out are subjected to the refresh operation, which contrasts with the refresh operations which generally, i.e. compulsorily, take place in dynamic semiconductor memories (DRAM). In an analogous manner, these advantages also apply to the further operating method which will also be described later.

In the case of this operating method (and in the operating method which will also be described below), it is advantageous to reset the information stored in the flag cells MMC that initiate the refresh operation to the abovementioned standard value during the refresh operation or after the latter. It is also expedient to render the process of carrying out a refresh operation

dependent on a further event that occurs or on a further criterion. Such a criterion may be, for example, a signal which is supplied to the memory arrangement and indicates that a control circuit, if
5 appropriate also a processor, to which the memory arrangement according to the invention is connected is currently in the quiescent state. In such a case, the refresh operation does not give rise to any loss of time since the memory arrangement would otherwise not
10 be operated actively in this period of time. Other criteria may also be (this list is only exemplary, not conclusive) the operation of switching on a device which contains the memory arrangement according to the invention, the switching-on operation giving rise to a
15 special signal which is generally referred to as a "power-on signal" and is directly or indirectly supplied to the memory arrangement according to the invention, or the operation of charging a device which contains the memory arrangement according to the
20 invention. In the latter case, a signal which then initiates the refresh operation may be derived, for example, from the fact that a charging current flows.

Figure 2 shows another advantageous embodiment of the
25 present invention: in this case, the flag cells MMC which are already known, in principle, from the first embodiment are arranged along the bit lines BL. In this case, the flag cells MMC can be addressed via the respective bit line BL and via a flag word line MWL
30 that is assigned to the respective flag cell MMC. The function of these flag cells MMC and their associated operating method correspond to those already described above with the proviso that, in this case, a refresh operation is carried out only with respect to those
35 memory cells MC which are arranged along a bit line BL with respect to which memory cells MC have previously been read. Information which indicates whether a reading operation has been carried out is also written to a flag cell MMC only with respect to those memory

cells MC which are arranged along the bit line BL that is associated with a respective flag cell MMC.

Figure 3 shows a third embodiment of the present invention. In this case, the memory arrangement according to the invention is implemented using a plurality of memory chips MEM which are functionally assigned to one another. This is the case, for example, in the memory modules which are generally known as such. Figure 3 illustrates such a memory module. Memory modules are usually driven by means of control circuits which are often referred to as controllers (not illustrated here). These control circuits may, for example, generate the abovementioned signals, which can generally be referred to as a "further event" and as such trigger the process of carrying out refresh operations, and supply said signals to the respective connected memory chips MEM. This embodiment also uses an individual memory chip MEM, which is symbolically shown on an enlarged scale using a magnifying glass, to illustrate that the individual memory chips MEM can contain, in addition to their memory cell array MCF, a so-called refresh device Refr which initiates and carries out a specifically desired refresh operation. The memory arrangements according to the first two embodiments of the present invention, in which the memory arrangement is equal to one memory chip MEM, may also have such a refresh device Refr. However, it is also conceivable for such a refresh device Refr to be outside the memory arrangement, for example inside the abovementioned control circuit.

List of reference symbols

BL, WL	Bit line, word line
MC	Memory cell
MMC	Flag cell
MBL, MWL	Flag bit line, flag word line
MCF	Memory cell array
MEM	Memory chip
Refr	Refresh device